SEMICONDUCTOR WORKPIECE CARRIERS AND METHODS FOR PROCESSING SEMICONDUCTOR WORKPIECES

ABSTRACT OF THE DISCLOSURE

Semiconductor workpiece carriers and methods for processing semiconductor workpieces are disclosed herein. In one embodiment, a semiconductor workpiece carrier assembly includes (a) a support structure having an opening sized to receive at least a portion of a semiconductor workpiece, and (b) a replaceable carrier positioned at the opening. The replaceable carrier includes a base and an adhesive layer on the base. The base has a surface, and the adhesive layer covers only a section of the surface of the base. The adhesive layer releasably attaches the replaceable carrier to the support structure.

Figure: 1A